

**SIEMENS**



High Speed Placement System.

# SIPLACE S

Best-in-class for Flexible High Speed.



High Speed Placement System.

# SIPLACE

# S

## Best-in-class for Flexible High Speed.

The SIPLACE S is the best-in-class solution among flexible high-speed systems. This very small compact machine features a footprint of only 4 m<sup>2</sup> and is designed for high volume placement with maximum modularity and flexibility. With its uniquely interchangeable placement heads, the SIPLACE S is able to perform the functions of three different machines.

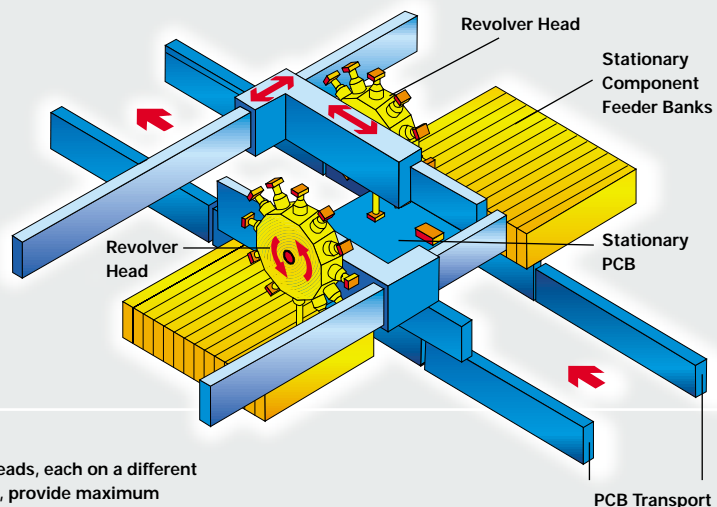
### Two heads are better than one.

The SIPLACE S comes equipped as a standard with two collect-and-place revolver heads which operate in parallel on two different gantries enabling placement rates of up to 25,000 cph per module.

### Interchangeable heads provide flexibility.

Interchangeable placement heads allow you to respond quickly to changing production requirements. SIPLACE S machines are designed for the following 3 combinations of collect-and-place heads.

- Chip Shooting: Two 12-nozzle heads for High-Speed placement of 0201s up to 18.7 x 18.7 mm
- IC Shooting: Two 6-nozzle heads for high-speed placement of 0603s up to 32 x 32 mm
- Line Balancing: One 6-nozzle head and one 12-nozzle head for components ranging between 0201 chips and 32 x 32 mm



Two heads, each on a different gantry, provide maximum speed and component range.



### Complete control with collect-and-place technology.

The SIPLACE S series optimizes speed and precision by means of the collect-and-place principle, which combines a highly accurate vision system with a 12-nozzle placement head permits precise control of all sequences during the placement process.

- Maximum placement reliability
- Optical centering of components and PCBs
- Feeder fiducials ensure highest pick reliability
- Mapping process for the positioning of the x and y axes

### State-of-the-art technology.

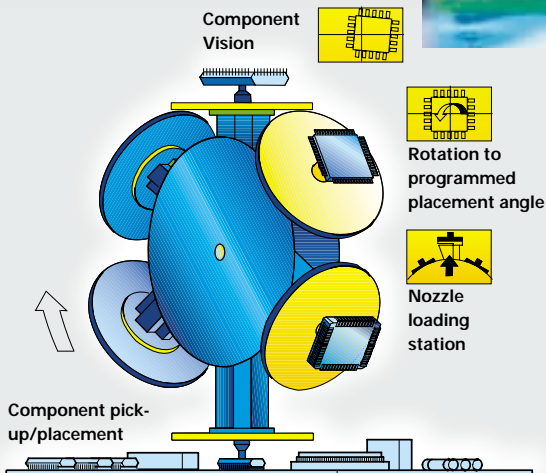
The SIPLACE S offers many innovations including changeover tables, which allow setups changes in a few minutes; efficient tape cutters and real-time line-monitoring systems, which help maximize throughput. PCBs and component feeders remain stationary during placement of all components, regardless of size or type.

### Profiting from the SIPLACE platform.

The SIPLACE S offers all the advantages of the comprehensive SIPLACE platform. Modular design at the machine and line levels, as well as the flexible placement heads, are just a few of the advantages the SIPLACE S shares with all other SIPLACE machines.



Sophisticated collect-and-place technology guarantees high-speed performance with maximum reliability.



Innovative technology enables SIPLACE S machines to achieve exceptionally high placement rates with highest accuracy. Modularity and a small footprint allow rapid line reconfiguration.

Siemens AG  
Production and Logistics  
Electronics Assembly  
PL EA  
Rupert-Mayer-StraÙe 44  
D-81359 Munich, Germany  
Tel. +49-89-722-27819  
Fax +49-89-722-41868  
Internet: <http://www.siplace.com>

Siemens Advanced Engineering Pte. Ltd.  
PL EA 1  
2, Kallang Sector, 5th Floor  
Singapore 349277  
Tel. +65-740-7406  
Fax +65-740-7412

Siemens Energy & Automation, Inc.  
Electronics Assembly Equipment  
2875 Northwoods Parkway  
Norcross, GA 30071, USA  
Tel. +1-770-797-3000  
Fax +1-770-797-3094